

Electronic Patent Application Fee Transmittal

Application Number:	10587744			
Filing Date:	28-Jul-2006			
Title of Invention:	METHOD FOR MANUFACTURING THIN FILM INTEGRATED CIRCUIT, AND ELEMENT SUBSTRATE			
First Named Inventor/Applicant Name:	Shunpei Yamazaki			
Filer:	Eric J. Robinson/Sue Ann Carr			
Attorney Docket Number:	0756-7782			
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Printed copy of patent - no color	8001	3	3	9
Total in USD (\$)				1819